



PC Board Layout $t=1.6\text{mm}$
Component Side Show

NOTES:

ELECTRICAL:

1. VOLTAGE RATING : 125 VAC RMS.
2. CURRENT RATING : 1.5 AMP.
3. CONTACT RESISTANCE : 30 MILLIOHMS MAX.
4. INSULATION RESISTANCE : 1000 MEGOHMS MIN @ 500 VDC.
5. DIELECTRIC STRENGTH : 1000 VAC RMS 60Hz, 1MIN.

MECHANICAL:

1. SHIELD MATERIAL : BRASS C2680 $t=0.25\text{mm}$.
2. PLASTIC MATERIAL : HIGH TEMP THERMOPLASTIC UL94V-0.(DUPON FR52)
3. CONTACT MATERIAL : PHOSPHOR BRONZE $t=0.35\text{mm}$.
4. PLATING : SHIELD PLATED 30u"~50u" NICKEL OR GROUNDING PEG OVER TIN.
CONTACT AREA- SELECTIVE GOLD PLATING.
TAILS-150u" TIN-LEAD MIN OVER 50u" NICKEL.
5. OPERATING LIFE : 750 CYCLES MIN.
6. PCB RETENTION PRE-SOLDER : 1 LB MIN.
7. PCB RETENTION POST-SOLDER: 10 LBS MIN.

ENVIRONMENTAL:

1. STORAGE : -40°C TO $+85^{\circ}\text{C}$.
2. OPERATION: 0°C TO 70°C .

MATES WITH MODULAR PLUG CONFORMING TO FCC PART 68, SUBPART F.

PART NUMBER: E6788-XXL72X-L

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|-----------------|-------------------------|--------|
| 4-"FRE" LOGO | 1- 3u" | 2- 6u" |
| 5-W/O"FRE" LOGO | 3-15u" | 4-30u" |
| | 5-50u" | |
| | 1- TINNED GROUNDING PEG | |
| | 2- NICKEL | |

DATENBLATT

Beschreibung: HIGH SPEED SIDE ENTRY MODULE JACK
w/shielded



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Artikel-Nr. SPEED:	N-E6788-52L722-L	Artikel-Nr. Kunde:	TD388S
Projekt-Nr. SPEED:	N-IN10D	Projekt-Nr. Kunde:	-
Datenblatt-Nr.:	DBLKS2216	Seite:	1 von 1

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